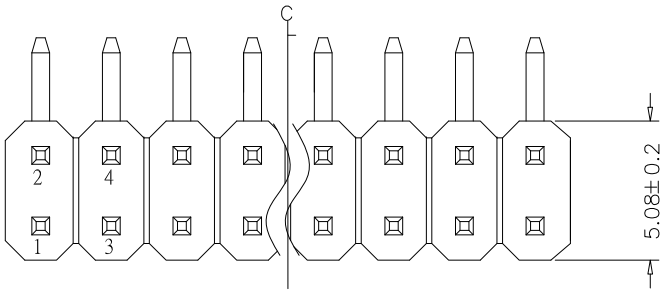
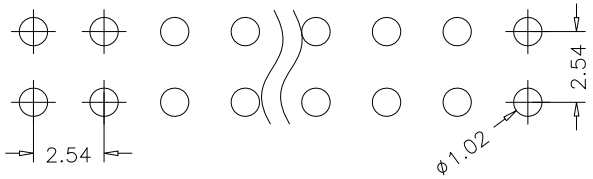
HSF

NOTES:
Current Rating:3.0AMP
Contact Resistance:20mΩ max
Withstand Voltage:500V AC/DC
Insulation Resistance:1000MΩ min
Operation Temperature:−40℃ to +105℃

Contact Material:Brass
Contact plating:Au or Sn Over Ni
Insulator Material:PBT or PA6T+30%GF(UL94V−0)



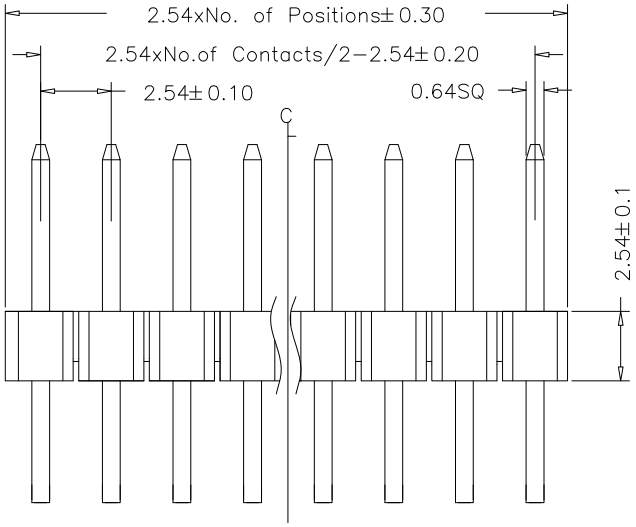
Recommended P.C.B Layout(Top Side)
(PCB BOARD TOLERANCE± 0.05)

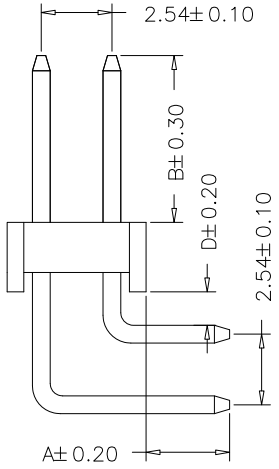


Ordering Information

BT1125 2 ** * ** D 2 A03

2	**	*	**	D	2	A03
2=Dual Row	No.of Pins 02~80	Contact Plating U=Gold Flash X=10u"Gold W=15u"Gold Y=20u"Gold Z=30u"Gold F=Gold Flash/Tin A=10u"Gold/Tin J=15u"Gold/Tin K=30u"Gold/Tin S=Tin Plated N=Nickel Plated	Pin Length See Table	Insulation & Packing B: PBT + Tube D: PBT + PE Bag J: PA6T + Tube L: PA6T + PE Bag	Contact Shape 2=Right Angle	





REV	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE
A0	09/01/19	NEW		

OPERATION		DRAW	Bill	09/01/19	SCALE	−
X.X	±0.40				UNIT	mm
X.XX	±0.25	DESIGN			SIZE	A4
X.XXX	±0.15	CHECK	Bill		SHEET	1/1
Angle	± 3°	APPROVE	Bill		PROJ.	
DIM	TOL					

BMA TECHNOLOGIES LTD

PART NO.	BT11252*****D2A03
TITLE:	PH2.54 DUAL ROW 90° CONCAVE BENDING H=2.5mm